

Tool ID: 305
Tool Location: 107

Equipment Information Sheet
Oxford PECVD

Manager:

Backup:

Backup:

Jeremy Clark

Phil Infante

Tom Pennell

607-254-6487

607-254-4926

607-254-4309

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- User must remain in lab while the plasma is on.
- The PECVD can be run at temperatures between 200 C and 400 C.
- The tool uses pyrophoric, toxic and oxidizing gases

USAGE RESTRICTIONS

- User is required to be in the lab during operation.
- For TEOS SiO2
 - Run "Clean - TEOS", changing the "INNER" and "OUTER" step time to total deposition time
- For a-Si
 - Run "Clean - aSi", changing the "INNER" and "OUTER" step time to total deposition time
- For all other materials
 - Run "High Rate Clean" for total deposition time plus 10 minutes.

SCHEDULING/SIGN-UP RESTRICTIONS

- 3 Hours Max from 8AM - 5PM
- 12 Hours Total Reservation per 7 days

Minimum Tool Time: 15 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No general material restrictions
- Resists or other polymers must be cured at 25C above the temperature of the hotplate.

Last Updated: 12/20/2022